Complementary Bias Resistor Transistors R1 = 2.2 k Ω , **R2 =** ∞ **k** Ω

NPN and PNP Transistors with Monolithic **Bias Resistor Network**

This series of digital transistors is designed to replace a single device and its external resistor bias network. The Bias Resistor Transistor (BRT) contains a single transistor with a monolithic bias network consisting of two resistors; a series base resistor and a base-emitter resistor. The BRT eliminates these individual components by integrating them into a single device. The use of a BRT can reduce both system cost and board space.

Features

- S and NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

(T_A = 25°C both polarities Q1 (PNP) and Q2 (NPN), unless otherwise noted)

Rating	Symbol	Max	Unit
Collector-Base Voltage	V _{CBO}	50	Vdc
Collector-Emitter Voltage	V _{CEO}	50	Vdc
Collector Current – Continuous	I _C	100	mAdc
Input Forward Voltage	V _{IN(fwd)}	12	Vdc
Input Reverse Voltage –NPN –PNP	V _{IN(rev)}	6 5	Vdc

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

ORDERING INFORMATION

Device	Package	Shipping [†]
NSBC123TPDP6T5G	SOT-963	8,000 / Tape & Reel

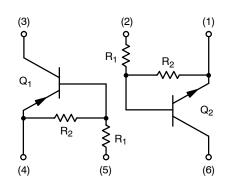
+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



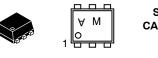
ON Semiconductor®

www.onsemi.com

PIN CONNECTIONS



MARKING DIAGRAMS



SOT-963 CASE 527AD

A Specific Device Code Μ

= Date Code*

*Date Code orientation may vary depending upon manufacturing location.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit	
NSBC123TPDP6 (SOT-963) One Junction Heated				
$\begin{array}{l} \mbox{Total Device Dissipation} \\ T_A = 25^\circ C & (Note 1) \\ & (Note 2) \\ \mbox{Derate above } 25^\circ C & (Note 1) \\ & (Note 2) \end{array}$	PD	231 269 1.9 2.2	mW mW/°C	
Thermal Resistance,(Note 1)Junction to Ambient(Note 2)	R _{θJA}	540 464	°C/W	

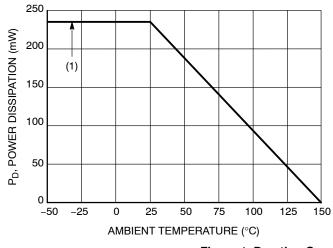
$\begin{array}{l} \mbox{Total Device Dissipation} \\ T_A = 25^\circ C & (Note 1) \\ & (Note 2) \\ \mbox{Derate above } 25^\circ C & (Note 1) \\ & (Note 2) \end{array}$	P _D	339 408 2.7 3.3	mW mW/°C
Thermal Resistance,(Note 1)Junction to Ambient(Note 2)	$R_{ hetaJA}$	369 306	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	–55 to +150	°C

FR-4 @ 100 mm², 1 oz. copper traces, still air.
 FR-4 @ 500 mm², 1 oz. copper traces, still air.
 Both junction heated values assume total power is sum of two equally powered channels.

ELECTRICAL CHARACTERISTICS	$(T_A = 25^{\circ}C \text{ both})$	polarities Q1 (PNP) and Q ₂ (NPN)	, unless otherwise noted)
-----------------------------------	------------------------------------	--------------------	----------------------------	---------------------------

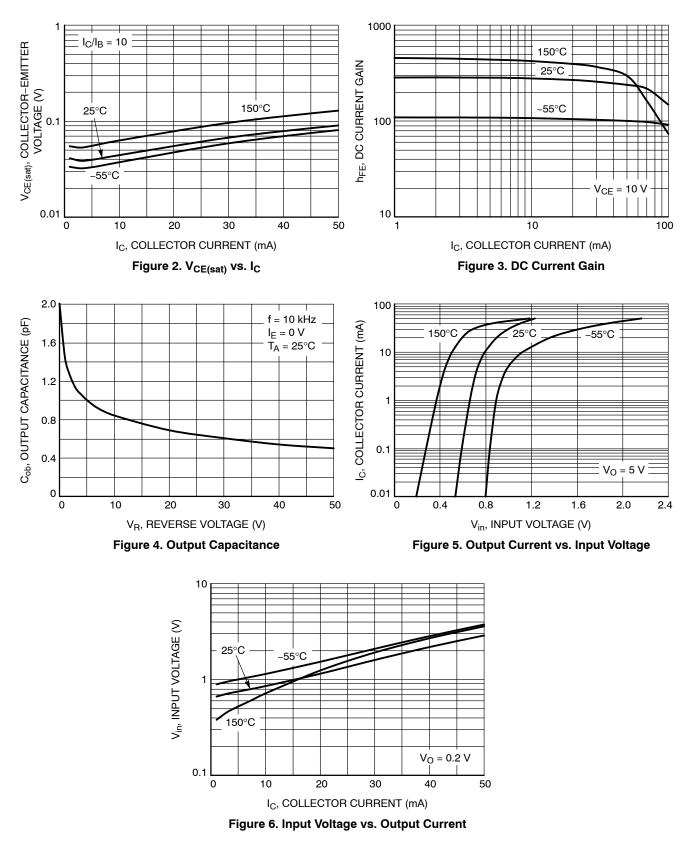
Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS	·				
Collector-Base Cutoff Current $(V_{CB} = 50 \text{ V}, I_E = 0)$	I _{CBO}	-	_	100	nAdc
Collector–Emitter Cutoff Current $(V_{CE} = 50 \text{ V}, I_B = 0)$	I _{CEO}	-	_	500	nAdc
Emitter-Base Cutoff Current ($V_{EB} = 6.0 \text{ V}, I_C = 0$)	I _{EBO}	-	_	4.0	mAdc
Collector-Base Breakdown Voltage $(I_C = 10 \ \mu A, I_E = 0)$	V _(BR) CBO	50	_	_	Vdc
Collector–Emitter Breakdown Voltage (Note 4) $(I_C = 2.0 \text{ mA}, I_B = 0)$	V _{(BR)CEO}	50	_	-	Vdc
ON CHARACTERISTICS	·				
DC Current Gain (Note 4) (I _C = 5.0 mA, V _{CE} = 10 V)	h _{FE}	160	350	-	
Collector–Emitter Saturation Voltage (Note 4) $(I_C = 10 \text{ mA}, I_B = 1.0 \text{ mA})$	V _{CE(sat)}	-	_	0.25	Vdc
Input Voltage (off) ($V_{CE} = 5.0 \text{ V}, I_C = 100 \mu \text{A}$) (NPN) ($V_{CE} = 5.0 \text{ V}, I_C = 100 \mu \text{A}$) (PNP)	V _{i(off)}		0.6 0.6		Vdc
Input Voltage (on) ($V_{CE} = 0.2 \text{ V}, I_C = 10 \text{ mA}$) (NPN) ($V_{CE} = 0.2 \text{ V}, I_C = 10 \text{ mA}$) (PNP)	V _{i(on)}		0.9 0.9		Vdc
Output Voltage (on) (V _{CC} = 5.0 V, V _B = 2.5 V, R _L = 1.0 k Ω)	V _{OL}	-	-	0.2	Vdc
Output Voltage (off) (V _{CC} = 5.0 V, V _B = 0.25 V, R _L = 1.0 k Ω)	V _{OH}	4.9	_	-	Vdc
Input Resistor	R1	1.5	2.2	2.9	kΩ
Resistor Ratio	R ₁ /R ₂	-	-	-	

4. Pulsed Condition: Pulse Width = 300 msec, Duty Cycle $\leq 2\%$.



(1) SOT-963; 100 mm², 1 oz. copper trace

TYPICAL CHARACTERISTICS – NPN TRANSISTOR NSBC123TPDP6



TYPICAL CHARACTERISTICS – PNP TRANSISTOR NSBC123TPDP6

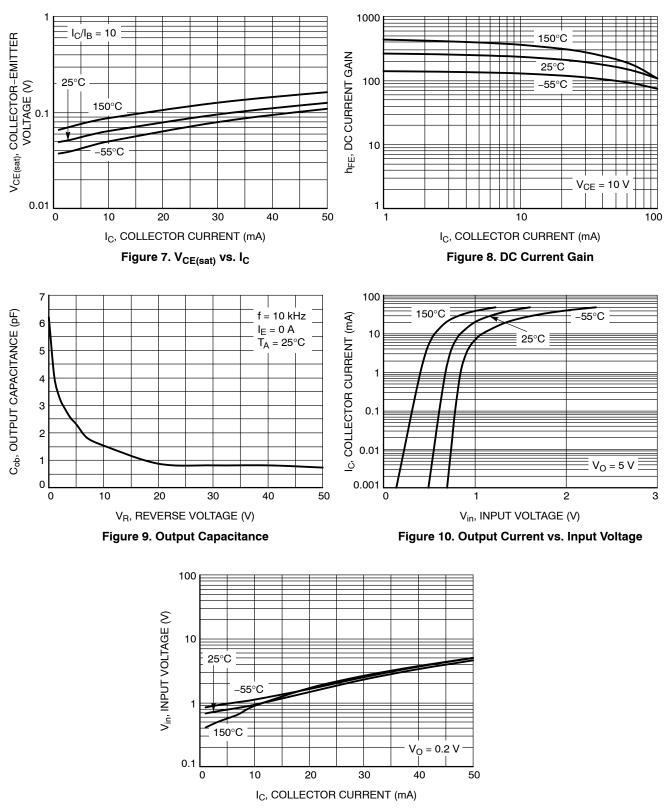
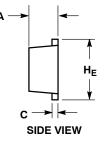


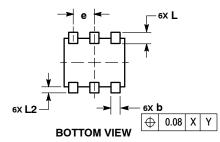
Figure 11. Input Voltage vs. Output Current

PACKAGE DIMENSIONS

SOT-963 CASE 527AD ISSUE E





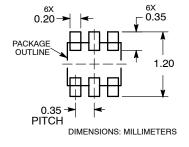


NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS
 MAXIMUM LEAD THICKNESS INCLUDES LEAD
- FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL
- BASE MATERIAL. 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.34	0.37	0.40	
b	0.10	0.15	0.20	
С	0.07	0.12	0.17	
D	0.95	1.00	1.05	
Е	0.75	0.80	0.85	
е	0.35 BSC			
ΗE	0.95	1.00	1.05	
L	0.19 REF			
L2	0.05	0.10	0.15	

RECOMMENDED MOUNTING FOOTPRINT



ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <u>www.onsemi.com/site/pdf/Patent-Marking.pdf</u>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor "Typical" parameters which may be provided in ON Semiconductor dates sheets and/or application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights or others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor hardles against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors h

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support:

Phone: 421 33 790 2910 Japan Customer Focus Center Phone: 81-3-5817-1050 ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative